Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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UP04112G

Silicon PNP epitaxial planar type

For digital circuits

■ Features

- Two elements incorporated into one package (Transistors with built-in resistor)
- SSMini type package, reduction of the mounting area and assembly cost

■ Basic Part Number

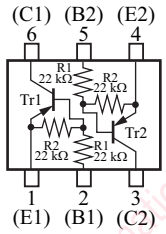
- UNR2112 × 2

■ Package

- Code
  SSMini6-F2
- Pin Name
  1: Emitter (Tr1) 4: Emitter (Tr2)
  2: Base (Tr1) 5: Base (Tr2)
  3: Collector (Tr2) 6: Collector (Tr1)

■ Marking Symbol: 6R

■ Internal Connection



■ Absolute Maximum Ratings $T_a = 25°C$

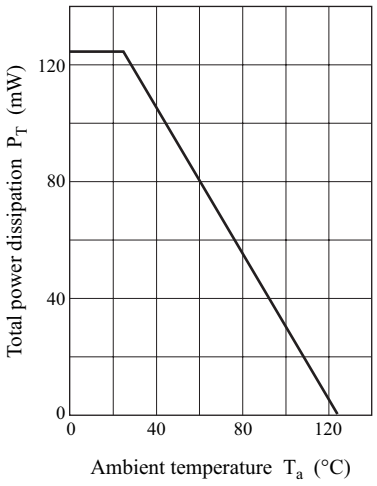
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	–50	V
Collector-emitter voltage (Base open)	V_{CEO}	–50	V
Collector current	I_C	–100	mA
Total power dissipation	P_T	125	mW
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	–55 to +125	°C

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

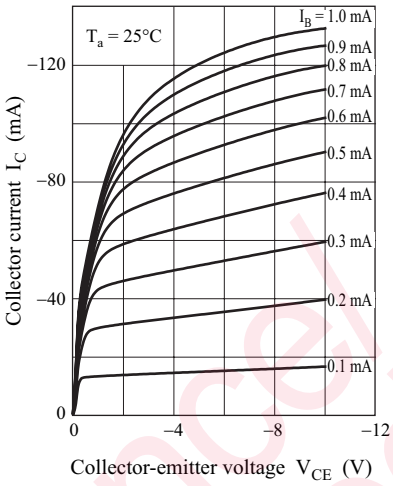
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = -10\ \mu A$, $I_E = 0$	–50			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -2$ mA, $I_B = 0$	–50			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -50$ V, $I_E = 0$			– 0.1	μA
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = -50$ V, $I_B = 0$			– 0.5	μA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -6$ V, $I_C = 0$			– 0.2	mA
Forward current transfer ratio	h_{FE}	$V_{CE} = -10$ V, $I_C = -5$ mA	60			—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -10$ mA, $I_B = -0.3$ mA			– 0.25	V
Output voltage high-level	V_{OH}	$V_{CC} = -5$ V, $V_B = -0.5$ V, $R_L = 1$ kΩ	–4.9			V
Output voltage low-level	V_{OL}	$V_{CC} = -5$ V, $V_B = -2.5$ V, $R_L = 1$ kΩ			– 0.2	V
Input resistance	R_1		–30%	22	+30%	kΩ
Resistance ratio	R_1 / R_2		0.8	1.0	1.2	—
Transition frequency	f_T	$V_{CB} = -10$ V, $I_E = 1$ mA, f = 200 MHz		80		MHz

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

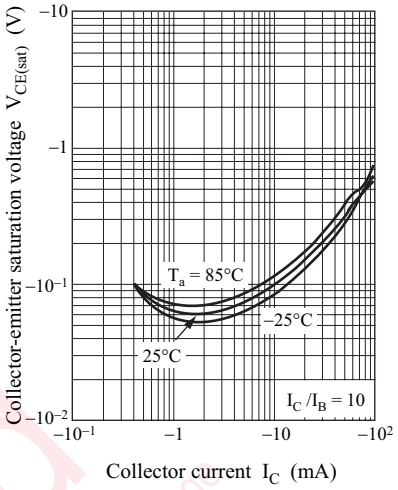
P_T — T_a



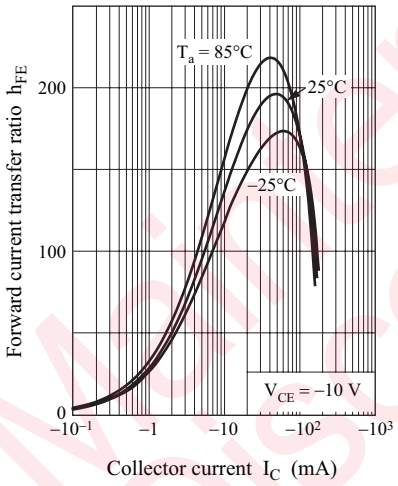
I_C — V_{CE}



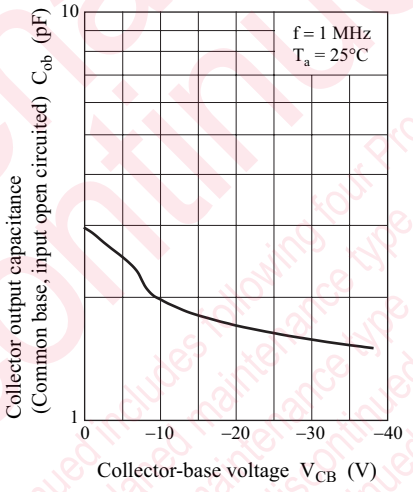
$V_{CE(sat)}$ — I_C



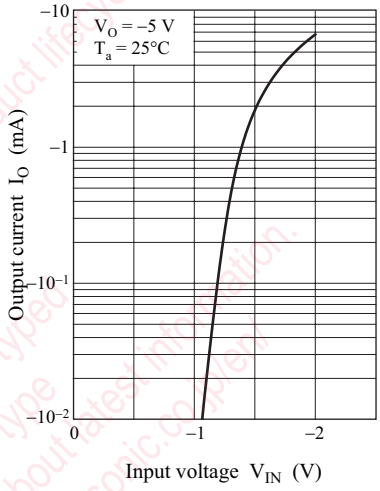
h_{FE} — I_C



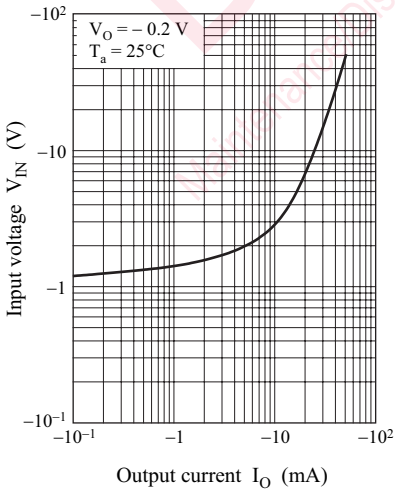
C_{ob} — V_{CB}



I_O — V_{IN}

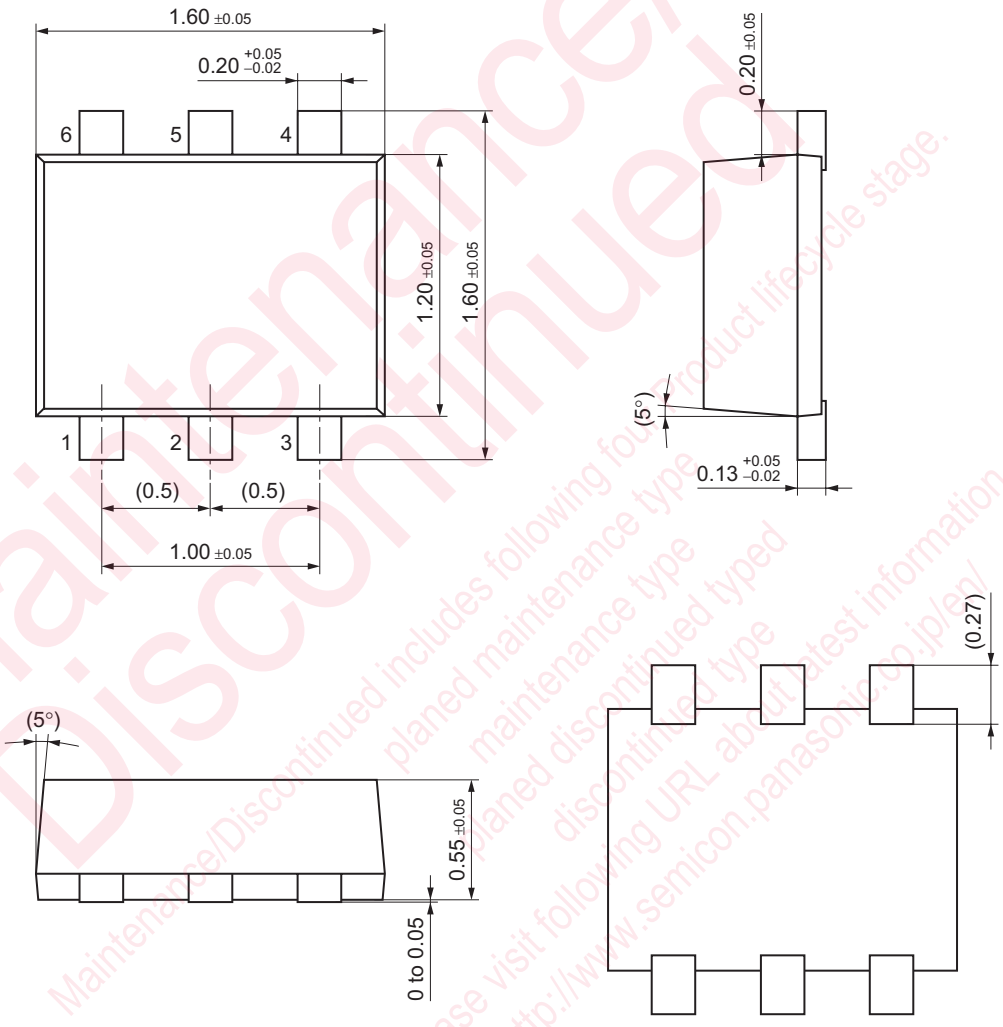


V_{IN} — I_O



SSMini6-F2

Unit: mm



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